0.10 4.83 1.27 0.95 stroke position Card lock position ര (n 13.72 Push 2x 2.00 ref. ref. 65 50 0 A ٩ 12.29 0.37 9.02 _A_ 8.50 0.79 2x Ø0.60 **∕^** 2x 0.75 4x 1.50 2x 12.75 Q Ŷ Q 14.50 A Ħ

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7x 0.45 2x 13.09

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Recommended PCB Layout (Viewed from Component Side - Tolerance:±0.05mm) Solder Area 🔀 Keep Out Area 📋 Component Outline





14 = 1.44 mm

4

4.20 ref. Card eject position

Specifications

Material

Housing&Slide : High Temperature Thermoplastic, UL94V-0, Black Contact Terminal: Copper Alloy Metallic Shell: Stainless Steel Spring: SWP-B Link: Stainless Steel

Plating

Contact : Contact Area: Gold Flash over Nickel Soldering Tail: Gold Flash over Nickel Shell:

Soldering Tail: Gold Flash over Nickel Spring&Link: Cleaning

Electrical

Voltage rating: 30V AC/DC Current Rating: 1.0 Amp AC/DC Max. Contact Resistance: Signal contact: 100 mΩ Max. CD to GND: 200 mQ Max. Dielectric Withstanding Voltage:500V AC (60 Sec Min.) Insulation Resistance: 1000 MΩ Min.@500V DC

Mechanical & Environmental Operating Temperature: -40°C to +85°C Durabillity : 5,000 cycles

Part Number			Product Description								
SIM806	6		Nano SIM Card Connector								
Drawing D	Date		Push-Push Type SMT 6Pin 1 44mm Profile								
19th March 2021											
By	CC	Tolerances (E	xcept as Noted)	Units:			This drawing is confidenti	is drawing is confidential and			
Detail	Drawing Release	X.X ± 0.30	Angle	Metric (mm)	ROHS COMPLIANT 2011/65/EU Deca-BDE	\bigcirc	copyright of Global Connector Technology, Ltd (GCT).	www.gct.co			
Revision	A2	X.XX ± 0.20	± 2°			or disclosed without written		en	Not to	Drawn By	Sheet No.
Date	15/03/22	X.XXX ± 0.10					consent. E & OE		Scale	CC	1/3
5			6			7				8	



